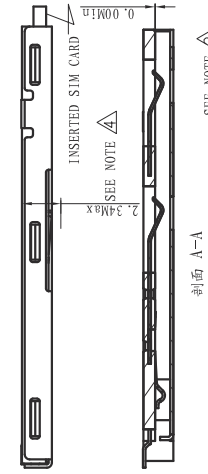


RECOMMENDED PCB LAYOUT
TOLERANCE +/-0.05MM

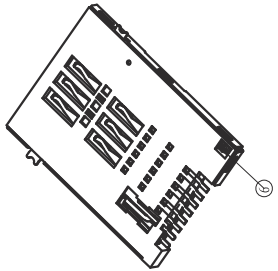
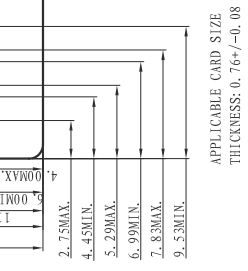


SEE NOTE A
SEE NOTE A

NOTE:

1. FINISH:
 - 1-1 TERMINAL:
 - 50~200μm NICKEL UNDER-PLATED
 - 5μm MIN GOLD PLATING ON CONTACT AREA
 - 100μm MIN Matte Tin ON SOLDERING AREA
 - 1-2 SHELL:
 - 50~200μm NICKEL UNDER-PLATED
 - 3μm MIN GOLD FLASH ON SOLDERING AREA
 - 1-3 DETECT PIN:
 - 50~200μm NICKEL UNDER-PLATED
 - 5μm MIN GOLD PLATING ON CONTACT AREA
 - 100μm MIN Matte Tin ON SOLDERING AREA
2. DETECT SWITCH: INSERT CARD=ON (NORMAL=OPEN)
3. I.E., TERMINAL TIP WILL SINK INTO HOUSING
4. SPRING RISE UP DURING PUSH-PUSH PERIOD
5. PRODUCT COMPLIANT TO ROHS DIRECTIVE 2002/95/EC AND ELV DIRECTIVE 2000/53/EC

SIM CARD		CARD INSERTED	WITHOUT CARD
Pin No.	NAME	QTY	MATERIAL
C1	VCC	1	HIGH TEMPERATURE THERMOPLASTIC
C2	RST	6	COPPER ALLOY
C3	CLK	1	COPPER ALLOY
C4	DETECT PIN LOWER	1	COPPER ALLOY
C5	GND	1	STAINLESS STEEL
C6	VPP	1	PLANO WIRE
C7	I/O	1	HIGH TEMPERATURE THERMOPLASTIC
		1	STAINLESS STEEL



TECHNICAL CHARACTERISTICS

1. General Characteristics
 - Dimensions: 26.50Lx19.35Wx1.80H mm
 - Weight: Approx 1.50g
 - Contact principle: friction technology
 - Operating position: shaft up/down/horizontal
 - Mounting System: SMT(Post optional)
 - Durability: 5000 cycles min.
2. Mechanical characteristics:
 - Insulation material: Thermoplastic, UL 94V-0

3. Electrical Characteristics

- Number of contacts (Optional): 6pins
- contact resistance: 50mΩ typical, 100mΩ max
- insulation resistance: >1000MΩ/500V DC
- Switch type: Blade
- Operation: Normally open
- 4. Solderability
 - wave: Not applicable
 - Vapor phase: 215°C, 30sec. Max
 - IR reflow: 260°C, 10sec. Max
 - Manual soldering : 360°C, 3sec. Max

5. Environmental Characteristics

- Operating temperature: -40°C~+85°C
- Operating humidity : 10%~95%RH
- Storage temperature: -40°C~+85°C
- Storage Humidity: 10%~95%RH
- thermal shock: -40°C~+85°C, 5cycles
- Damp Heat: 40°C, 90%RH, 10days.
- Salt - Mist: 35°C, 5%NaCl, 24HR

Wellco T&C Co., Ltd.

P/N # 750-NP

SIM Card Connector

REVISION: 1.0

DATE: Jul.8, 2009